



PATENT APPLICATION

#91C
Bell
5/203

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2823

Application No.: 09/991,931

Examiner: H. Lee

Filed: November 26, 2001

Docket No.: 103092.02

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the December 13, 2002 Office Action, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 25, lines 17-23, delete current paragraph and insert therefor:

In this way, after the penetrating holes 214a are formed, the conductive member 18 is formed on the substrate 214, to constitute two-layer substrate. For example, if the substrate 214 is of a thermoplastic substance, it can be softened by heating, and a conductive foil adhered without the use of adhesive, and by etching thereof a conductive member 18 can be formed. Alternatively, sputtering may equally be applied.

IN THE CLAIMS:

Please replace claims 53, 55, 58, 59, 66, 67 and 70-73 as follows:

53. (Amended) A substrate having penetrating holes formed therein, the substrate having a wiring pattern adhered on one side thereof by an adhesive material over a particular

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